



REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
0	INITIAL RELEASE	03/06/13	Joe L.
2	changed only logo from optina to Onsemi	03/14/18	sesha

NOTES: UNLESS OTHERWISE SPECIFIED.

1. MATERIAL: FR-4(PCL370-HR) ROHS COMPLIANT.
 2. LAYER THICKNESS AND STACKUP: SEE STACKUP DRAWING VIEW A-A
 3. FINISH: IMMERSION GOLD
 4. COMPONENT SIDE SHOWN.
 5. ALL INNER LAYERS TO BE TREATED WITH BLACK OXIDE.
 6. HOLE DIAMETERS ARE AFTER PLATING, .001 MINIMUM.
 7. SILKSCREEN BOTH SIDES WITH WHITE NON-CONDUCTIVE SILKSCREEN.
NOTE: LEGEND SHOULD BE REMOVED FROM ANY CONDUCTIVE SURFACE UNLESS OTHERWISE SPECIFIED.
 8. APPLY SOLDERMASK OVER BARE COPPER BOTH SIDES PER THE GERBER DATA AND IPC-SM-840, TYPE A, CLASS B. THERE SHALL BE NO SOLDER MASK ON ANY LAND.
COLOR: BLACK MATT
TYPE: LP1
THICKNESS: 0.002 MAX.
 9. TOOLING HOLES ARE TO BE DRILLED AT THE SAME TIME AS ALL OTHER HOLES ON PCB.
 10. HOLE DIAMETER CALL OUTS ARE AFTER PLATING.
NO PLATING RINGS ARE PERMISSIBLE AROUND UNPLATED HOLES UNLESS SPECIFIED OTHERWISE.
 11. ACCEPTABILITY SHALL BE BASED ON IPC-A-600, CLASS 2.
 12. IMPEDANCE CONTROL: +/- 10%
- ALL 6 MIL TRACES ON TOP AND BOTTOM LAYERS ARE TO HAVE 50 OHM SINGLE ENDED
ALL 5.25 MIL TRACES WITH 12.75 MIL SPACING TO HAVE 100 OHM DIFFERENTIAL IMPEDANCE

DRILL CHART- TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
•	6.0	+1.0/-1.0	PLATED	68
◦	10.0	+3.0/-3.0	PLATED	186
•	15.0	+3.0/-3.0	PLATED	137
•	32.0	+3.0/-3.0	PLATED	74
•	40.0	+3.0/-3.0	PLATED	42
•	68.0	+4.0/-4.0	PLATED	4
⊖	95.0	+4.0/-4.0	PLATED	4
⊖	118.0	+4.0/-4.0	PLATED	2
⊖	125.0	+4.0/-4.0	PLATED	5
⊖	138.0	+5.0/-5.0	PLATED	1
•	47.0	+2.0/-2.0	NON-PLATED	4
•	64.0	+3.0/-3.0	NON-PLATED	2

UNLESS OTHERWISE SPECIFIED		SIGNATURES		DATE	
DIMENSIONS ARE IN INCHES		Layout:	Ganapathi	03/14/18	
		CHECKED			
		ENGR:	Sesha	03/14/18	
		ISSUED		03/14/18	
		SIZE	FSCN NO	DWG NO	
				AP1302	
		SCALE			SHEET

ICP3_120VFBGA_DEMO_Rev2
FAB DRAWING

AP1302